P-Channel Enhancement Mode MOSFET

MTP2611V8

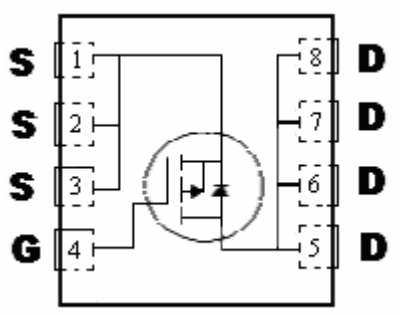
BV_{DSS}	-20V
I_D	-45A
R_{DSON}@V_{GS}=-4.5V, I_D=-15.3A	8.8mΩ(typ)
R_{DSON}@V_{GS}=-2.5V, I_D=-13.1A	12.8mΩ(typ)

Features

- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Pb-free lead plating and halogen-free package

Equivalent Circuit

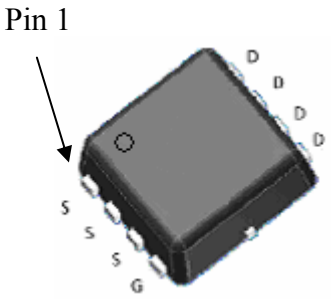
MTP2611V8



G：Gate S：Source D：Drain

Outline

DFN3×3



Ordering Information

Device	Package	Shipping
MTP2611V8-0-T6-G	DFN3×3 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T6 : 3000 pcs / tape & reel,13” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V_{DS}	-20	V
Gate-Source Voltage		V_{GS}	±12	
Continuous Drain Current @ T_C=25°C, V_{GS}=-4.5V		I_D	-45	A
Continuous Drain Current @ T_C=100°C, V_{GS}=-4.5V			-28	
Continuous Drain Current @ T_A=25°C, V_{GS}=-4.5V			-12	
Continuous Drain Current @ T_A=70°C, V_{GS}=-4.5V			-9.6	
Pulsed Drain Current		I_{DM}	-90 *1	
Total Power Dissipation	T_C=25℃	P_D	31	W
	T_C=100℃		12	
	T_A=25℃		2.5 *3	
	T_A=70℃		1.6 *3	
Operating Junction and Storage Temperature Range		Tj, Tstg	-55~+150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	4	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{th,j-a}$	50 *3	°C/W

Note : 1. Pulse width limited by maximum junction temperature
2. Duty cycle≤1%
3. Surface mounted on 1 in² copper pad of FR-4 board, t≤10s ; 125°C/W when mounted on minimum copper pad.

Electrical Characteristics (Tj=25°C, unless otherwise specified)

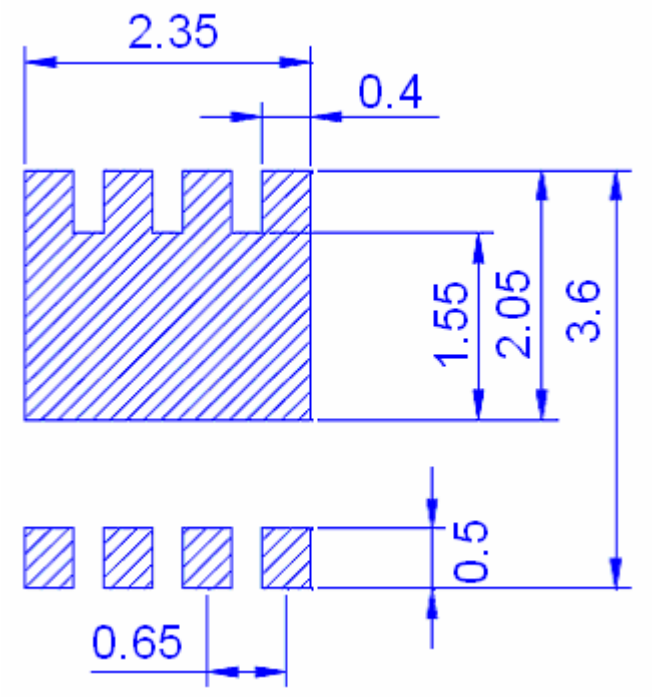
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-20	-	-	V	V_{GS}=0, I_D=-250μA
$V_{GS(th)}$	-0.4	-0.62	-1.5		V_{DS}=V_{GS}, I_D=-250μA
I_{GSS}	-	-	±100	nA	V_{GS}=±12V, V_{DS}=0
I_{DSS}	-	-	-1	μA	V_{DS}=-16V, V_{GS}=0
I_{DSS}	-	-	-25		V_{DS}=-16V, V_{GS}=0, Tj=125°C
$R_{DS(ON)}$ *1	-	8.8	11	mΩ	V_{GS}=-4.5V, I_D=-15.3A
	-	12.8	17		V_{GS}=-2.5V I_D=-13.1A
G_{FS} *1	-	22	-	S	V_{DS}=-10V, I_D=-10A
Dynamic					
Ciss	-	4107	-	pF	V_{DS}=-10V, V_{GS}=0, f=1MHz
Coss	-	415	-		
Crss	-	368	-		
$t_{d(ON)}$ *1, 2	-	42	-	ns	V_{DS}=-10V, I_D=-1A, V_{GS}=-4.5V, R_G=6Ω
tr *1, 2	-	23	-		
$t_{d(OFF)}$ *1, 2	-	136	-		
t_f *1, 2	-	74	-		

Electrical Characteristics(Cont.) (Tj=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Qg *1, 2	-	44	-	nC	V_{DS}=-10V, I_D=-12A, V_{GS}=-4.5V
Qgs *1, 2	-	8.9	-		
Qgd *1, 2	-	11	-		
Source-Drain Diode					
V_{SD} *1	-	-0.67	-1	V	I_S=-1.5A, V_{GS}=0V
trr	-	80	-	ns	I_F=-12A, dI_F/dt=100A/μs
Qrr	-	65	-	nC	

Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%
*2.Independent of operating temperature
*3.Pulse width limited by maximum junction temperature.

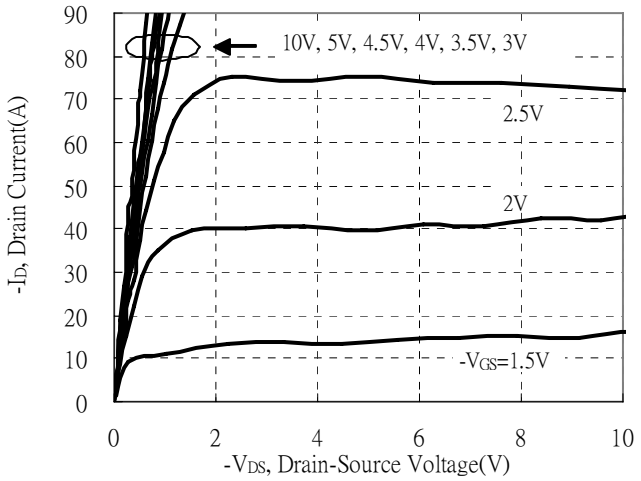
Recommended Soldering Footprint



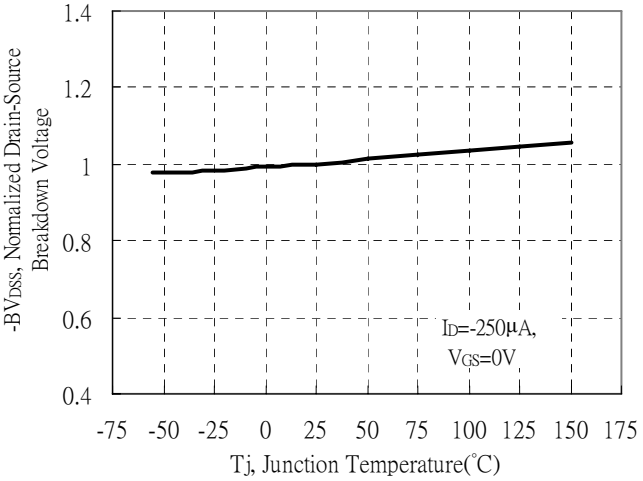
unit : mm

Typical Characteristics

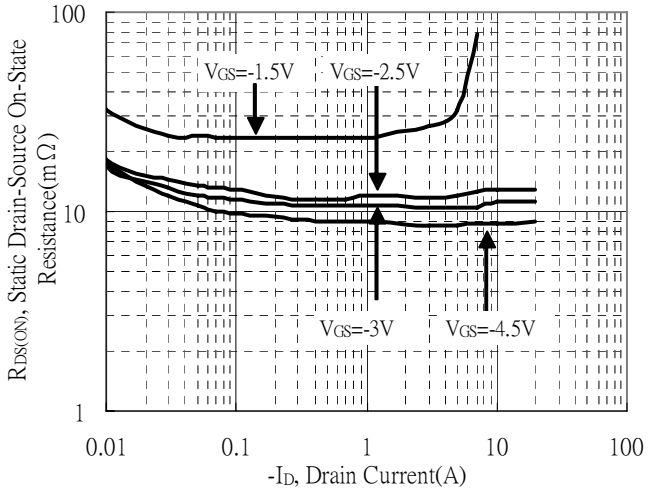
Typical Output Characteristics



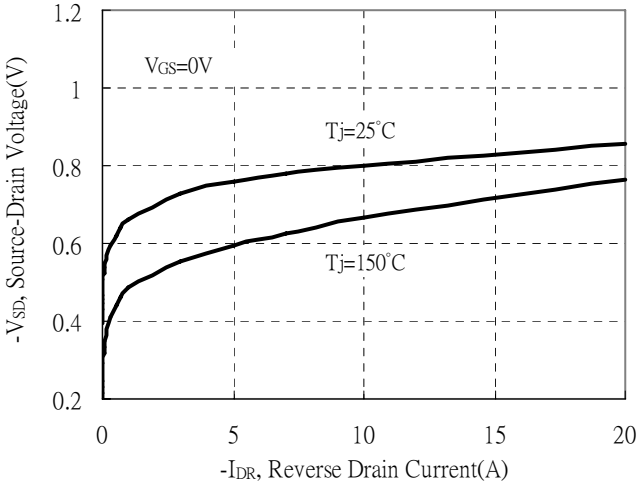
Brekdown Voltage vs Ambient Temperature



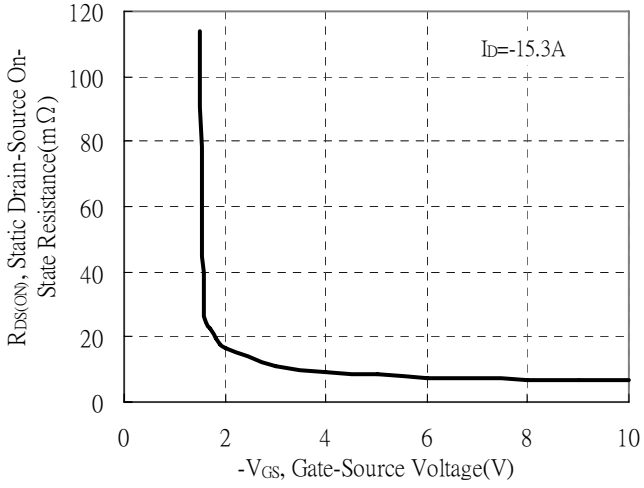
Static Drain-Source On-State resistance vs Drain Current



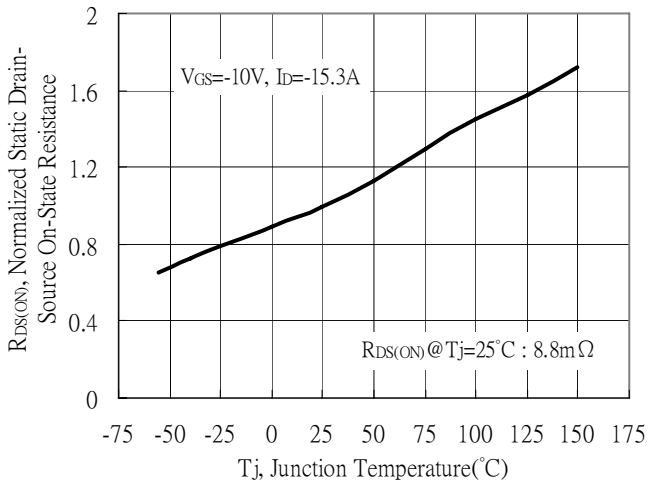
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

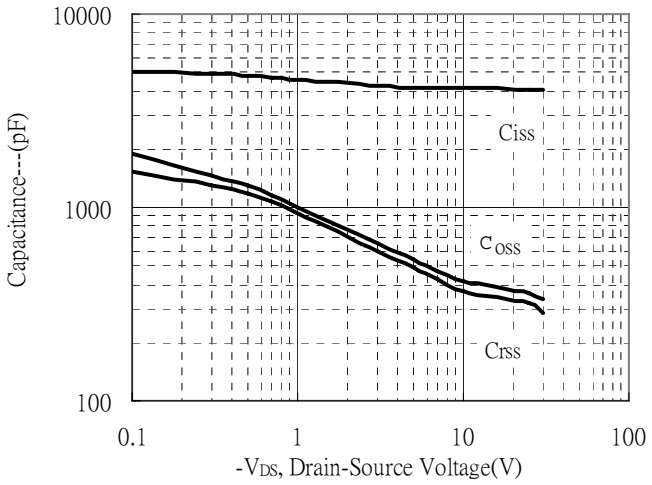


Drain-Source On-State Resistance vs Junction Tempearture

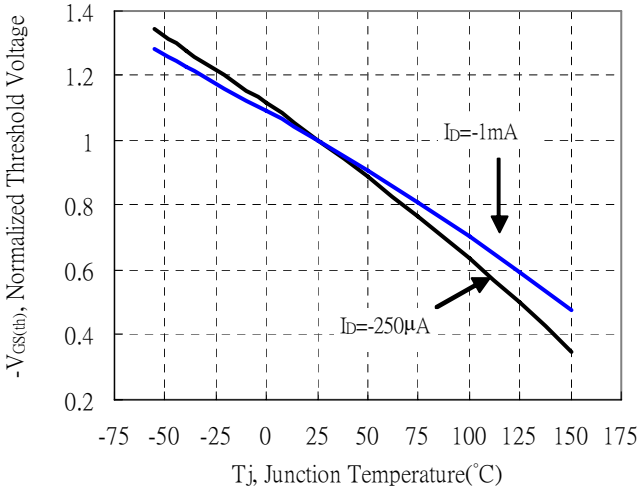


Typical Characteristics(Cont.)

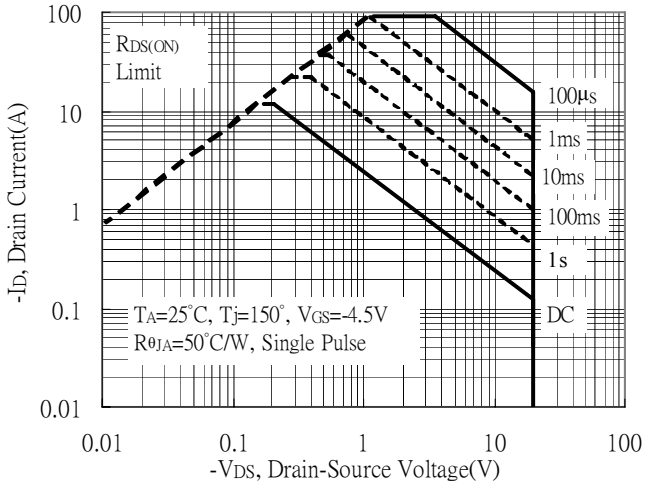
Capacitance vs Drain-to-Source Voltage



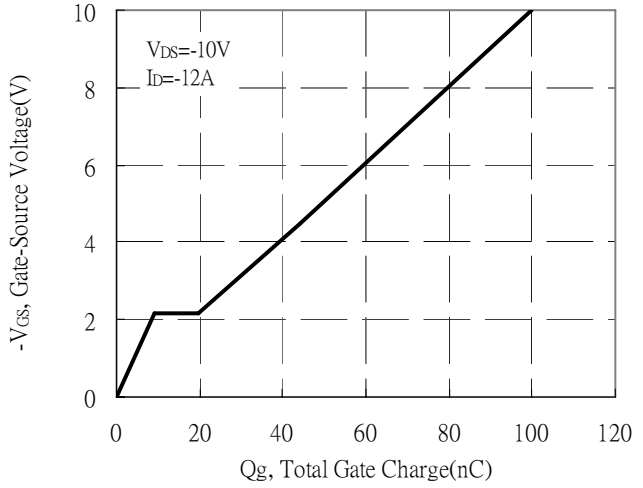
Threshold Voltage vs Junction Tempearture



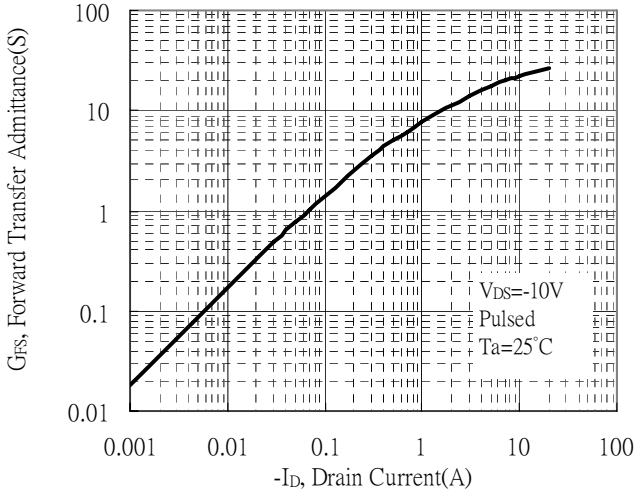
Maximum Safe Operating Area



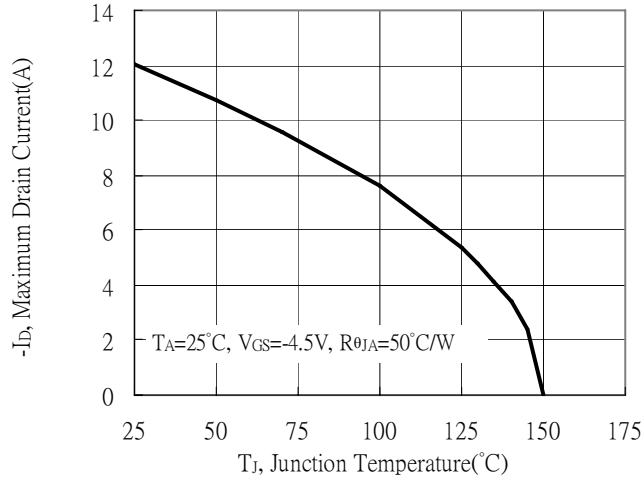
Gate Charge Characteristics



Forward Transfer Admittance vs Drain Current

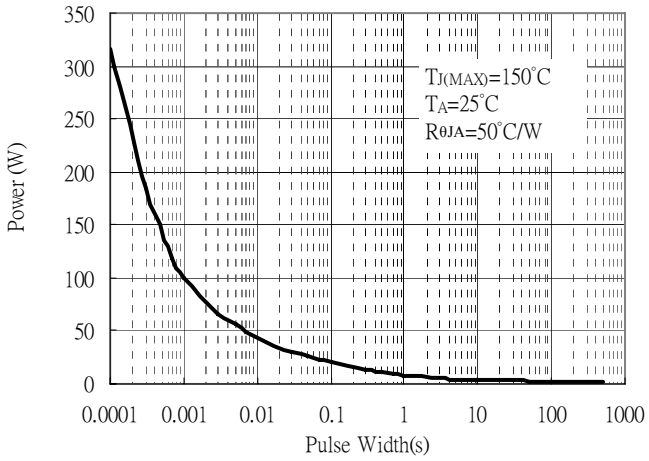


Maximum Drain Current vs Junction Temperature

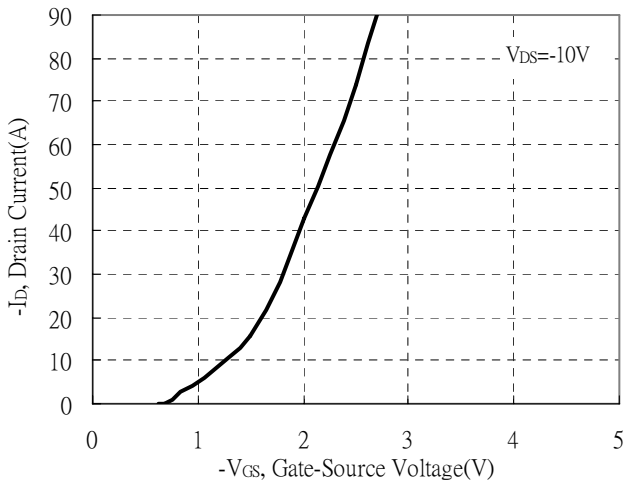


Typical Characteristics(Cont.)

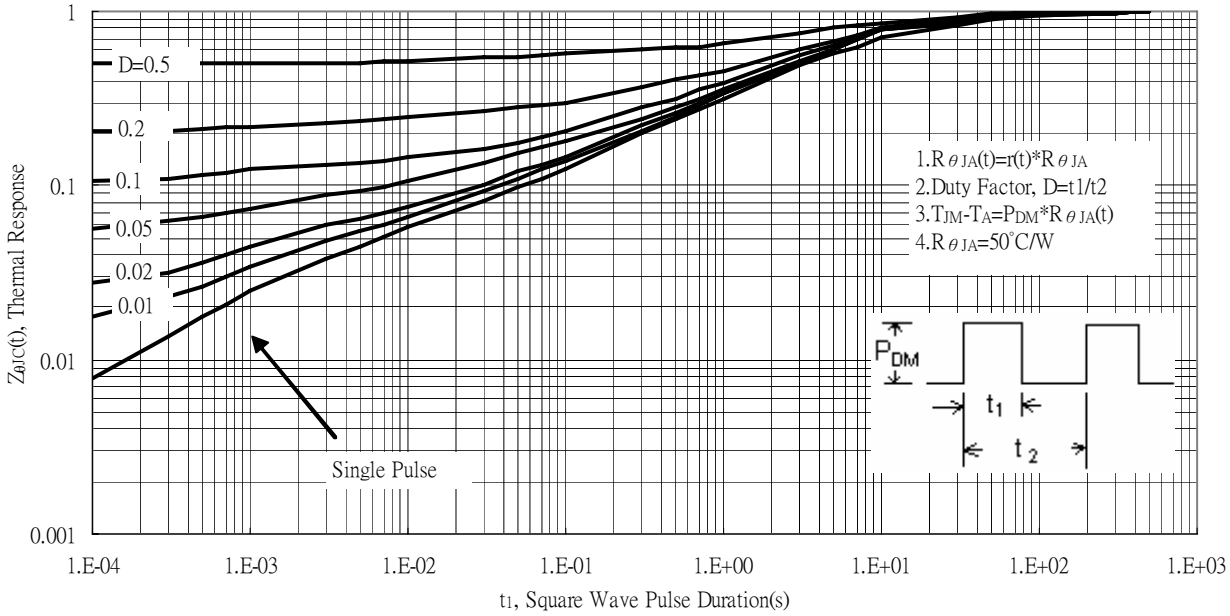
Single Pulse Power Rating, Junction to Ambient
(Note on page 2)



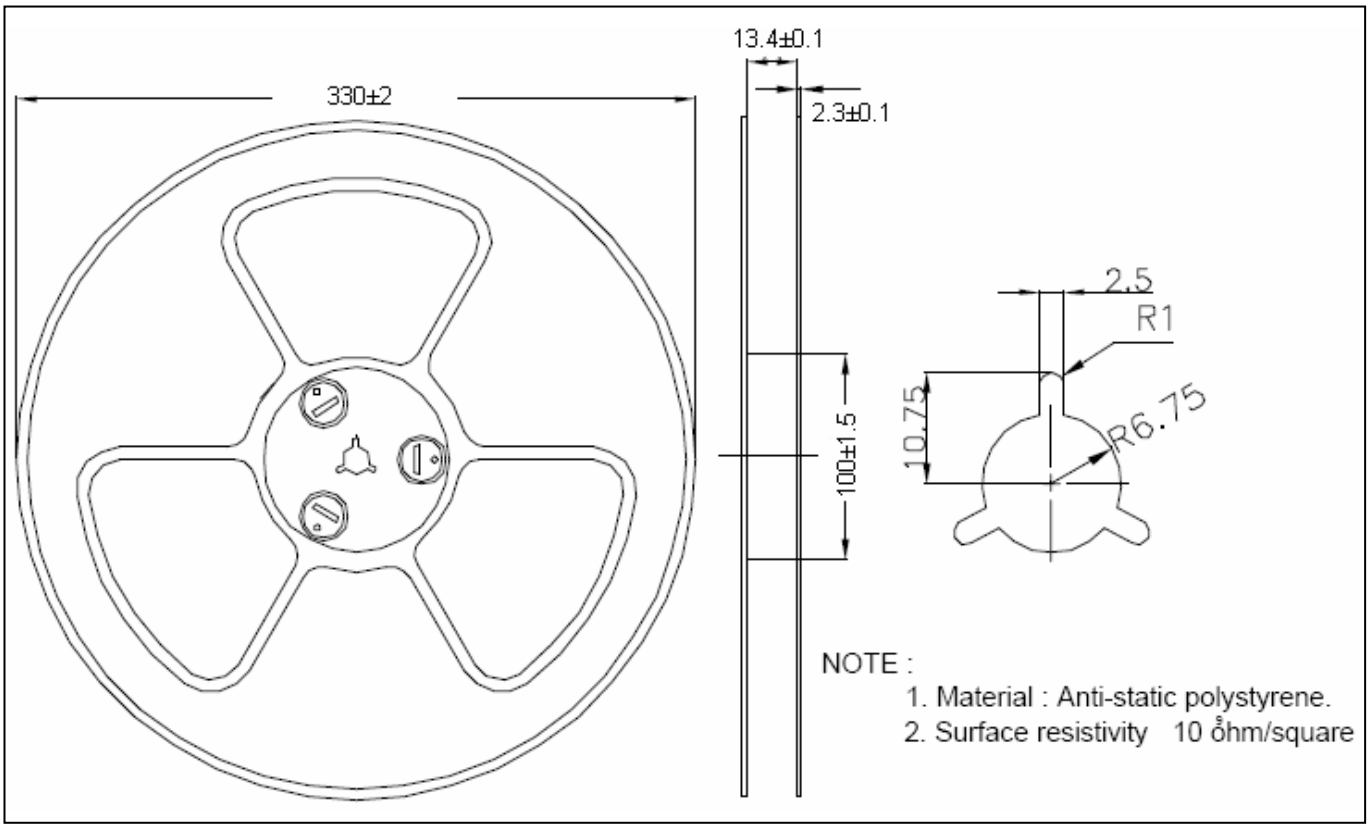
Typical Transfer Characteristics



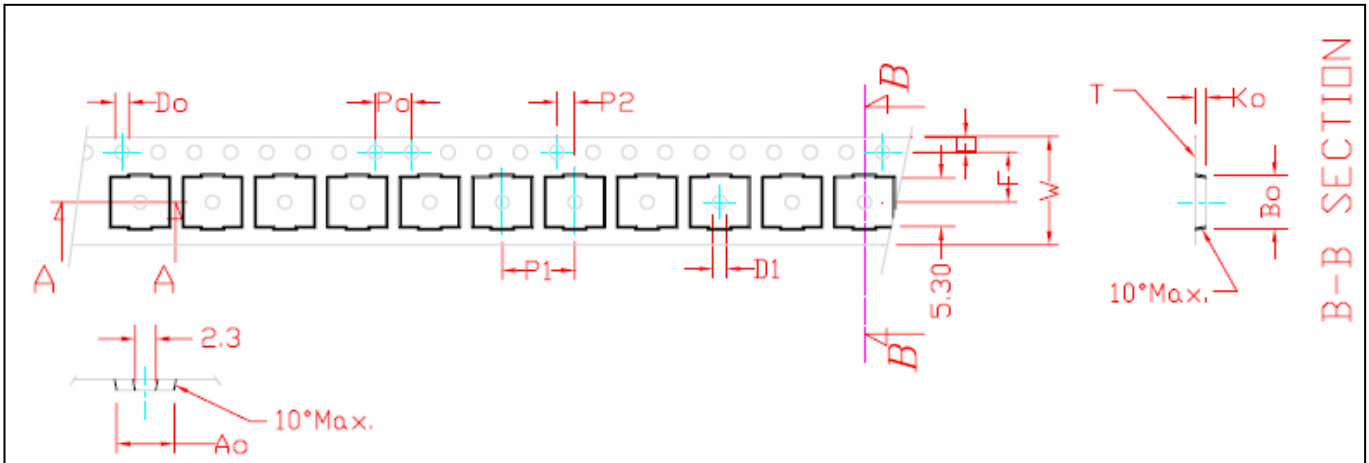
Transient Thermal Response Curves



Reel Dimension



Carrier Tape Dimension

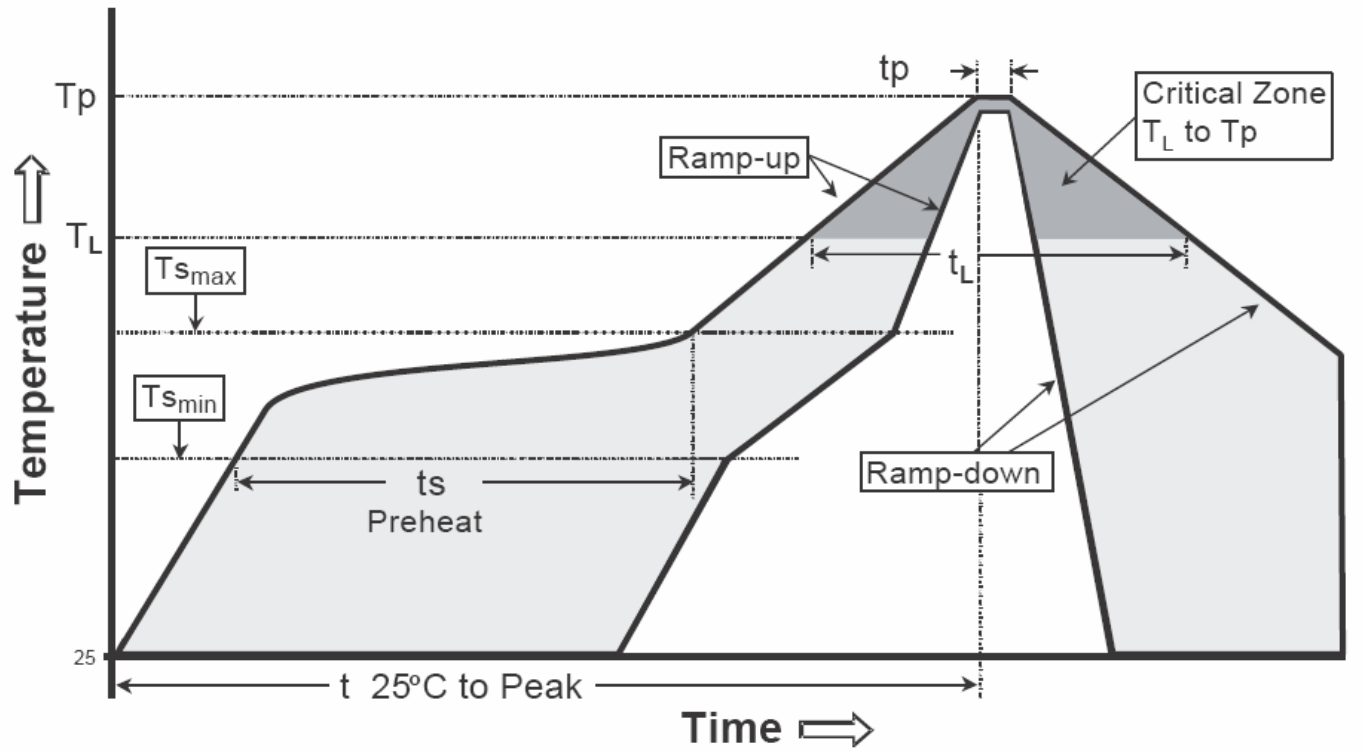


symbol	Ao	Bo	Ko	Po	P1	P2	T
Spec	6.33±0.1	5.78±0.1	1.18±0.1	4.00±0.1	8.0±0.10	2.0±0.05	0.29±0.02
symbol	E	F	Do	D1	W	10Po	
Spec	1.75±0.1	5.5±0.05	1.50±0.10	1.5±0.25	12.0 $^{+0.3}_{-0.1}$	40.0±0.2	

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

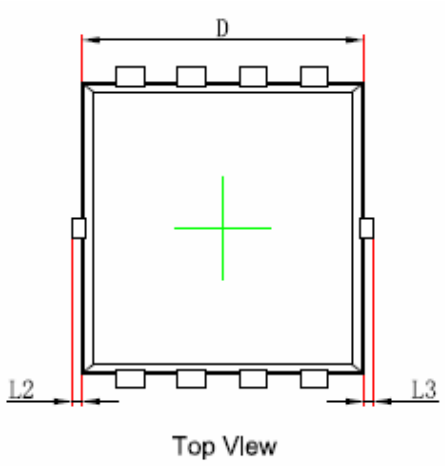
Recommended temperature profile for IR reflow



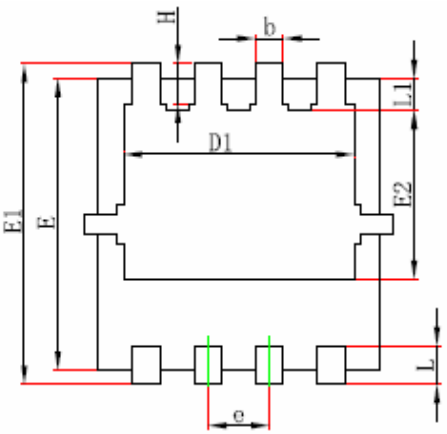
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(Ts min) −Temperature Max(Ts max) −Time(ts min to ts max)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (TL) − Time (tL)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

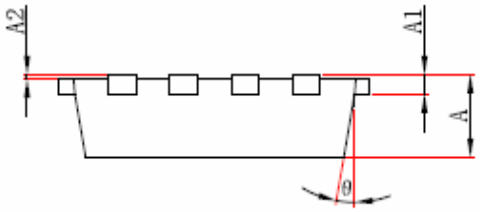
DFN3x3 Dimension



Top View

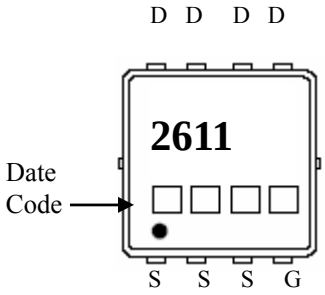


Bottom View



Side View

Marking:



8-Lead DFN3x3 Plastic Package
CYStek Package Code: V8

*: Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.605	0.850	0.026	0.033	b	0.200	0.400	0.008	0.016
A1	0.152 REF		0.006 REF		e	0.550	0.750	0.022	0.030
A2	0.000	0.050	0.000	0.002	L	0.300	0.500	0.012	0.020
D	2.900	3.100	0.114	0.122	L1	0.180	0.480	0.007	0.019
D1	2.300	2.600	0.091	0.102	L2	0.000	0.100	0.000	0.004
E	2.900	3.100	0.114	0.122	L3	0.000	0.100	0.000	0.004
E1	3.150	3.450	0.124	0.136	H	0.315	0.515	0.012	0.020
E2	1.535	1.935	0.060	0.076	θ	9°	13°	9°	13°

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.